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### Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

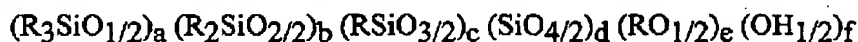
### Listing of Claims:

#### Claim 1-27 (Canceled)

28. (Currently Amended) A flame retardant composition comprising:

(a) 81 to 99.99 weight percent of a thermoplastic resin, thermoset resin, thermoplastic resin blend, or thermoset resin blend which upon burning forms a char; and

(b) 0.01-19 weight percent of a silsesquioxane resin having a weight average molecular weight of greater than 300 and having the average molecular formula:



wherein each R is hydrogen, ~~methyl, or phenyl~~ an alkyl group, an alkenyl group, or an aryl group ~~having from 6 to 12 carbon atoms~~, a and b are zero or positive numbers and the value of a+b is greater than zero, c is a positive number, d, e and f are zero or positive numbers with the provisos that the copolymer comprises at least 40 mole percent of  $RSiO_{3/2}$  units, the copolymer comprises less than 10 mole percent  $SiO_{4/2}$  units, greater than 30 mole percent of the silicon-bonded R groups are silicon-bonded ~~phenyl~~ aryl groups, greater than 0.5 mole percent of the silicon-bonded R groups are silicon-bonded hydrogen atoms, the content of silicon-bonded hydroxyl groups is equal to or less than 2 weight percent, and the content of silicon-bonded alkoxy groups where the alkoxy group is methoxy or ethoxy is equal to or less than 5 weight percent.

29. (Previously Presented) A composition according to Claim 28, wherein (a) is selected from polycarbonates, polyamides, polyesters, blends of polycarbonates with other polymers, polyphenylene ether, polyphenyleneoxide, blends of polyphenylene ether with styrenics, blends of polyphenyleneoxide with styrenic materials, polyaramids, polyimides, phenyl-containing resins having a rigid rod structure, styrenic materials, polyacrylates, styrene-acrylonitrile resins,

halogenated plastics, polyketones, polymethylmethacrylate (PMMA), thermoplastic elastomers, celluloses, rayon, or polylactic acid.

30. (Withdrawn) A composition according to Claim 29, wherein the styrenic materials are selected from acrylonitrile-butadiene-styrene, polystyrene, or high-impact polystyrene.

31. (Withdrawn) A composition according to Claim 28, wherein (a) is selected from epoxy resins, phenolic resins, urethane elastomers, or blends thereof.

32. (Canceled)

33. (Previously Presented) A composition according to Claim 28, wherein (b) comprises 60 to 90 mole percent of  $\text{RSiO}_{3/2}$  units, less than 5 mole percent of  $\text{SiO}_{4/2}$  units, 50 to 80 mole percent silicon-bonded phenyl groups, 1 to 5 mole percent silicon-bonded hydrogen atoms, 0.5 to 1.2 weight percent silicon-bonded hydroxyl groups, and less than 5 percent silicon-bonded alkoxy groups where the alkoxy group is methoxy or ethoxy.

34. (Previously Presented) A composition according to Claim 28, wherein (b) is  $(\text{Me}_2\text{HSiO}_{1/2})_a(\text{PhMeSiO}_{2/2})_b(\text{Me}_2\text{SiO}_{2/2})_c(\text{PhSiO}_{3/2})_d$ ,  $(\text{MeHSiO}_{2/2})_b(\text{PhSiO}_{3/2})_c$ , or  $(\text{Me}_3\text{SiO}_{1/2})_a(\text{MeHSiO}_{2/2})_b(\text{PhSiO}_{3/2})_c$ .

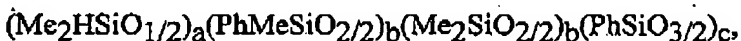
35. (Previously Presented) A composition according to Claim 28, wherein the composition further comprises a sodium-containing catalyst.

36. (Previously Presented) A composition according to Claim 28, wherein the compositions further comprise polytetrafluoroethylene powder.

37. (Previously Presented) A composition according to Claim 28, wherein (a) is selected from polycarbonates, polycaprolactam, polylauryllactam, polyhexamethylenedipamide, polyhexamethylenedodecanamide, blends of Nylons with other polymers, polybutylene terephthalate, polyethylene terephthalate, polyethylene naphthalate, polycarbonate-acrylonitrile-butadiene-styrene blends, polycarbonate-polybutylene terephthalate blends, polyphenylene ether, polyphenyleneoxide, polyphenylene sulfide, polyether sulphone, polyethylene sulfide, acrylonitrile-butadiene-styrene, polystyrene, high-impact polystyrene, styrene-acrylonitrile resins, polyvinyl chloride, fluoroplastics, polymethylmethacrylate, thermoplastic urethanes, thermoplastic vulcanizates, or styrene ethylene butylene styrene copolymer.

38. (Currently Amended) A composition according to Claim 37, wherein (b) comprises 60 to 90 mole percent of  $\text{RSiO}_{3/2}$  units, less than 5 mole percent of  $\text{SiO}_{4/2}$  units, 50 to 80 mole percent silicon-bonded phenyl groups, 1 to 5 mole percent silicon-bonded hydrogen atoms, 0.5 to 1.2 weight percent silicon-bonded hydroxyl groups, and less than 5 percent silicon-bonded alkoxy groups where the alkoxy group is methoxy or ethoxy.

39. (Previously Presented) A composition according to Claim 37, wherein (b) is



40. (Previously Presented) A composition according to Claim 38, wherein the composition further comprises a sodium-containing catalyst.

41. (Previously Presented) A composition according to Claim 39, wherein the composition further comprises a sodium-containing catalyst.

42. (Previously Presented) A composition according to Claim 40, wherein the compositions further comprise polytetrafluoroethylene powder.

43. (Previously Presented) A composition according to Claim 41, wherein the compositions further comprise polytetrafluoroethylene powder.

44. (New) A composition according to Claim 28 wherein (b) comprises 60 to 90 mole percent of  $\text{RSiO}_{3/2}$  units, less than 5 mole percent of  $\text{SiO}_{4/2}$  units, 50 to 80 mole percent silicon-bonded phenyl groups, 13 to 20 mole percent silicon-bonded hydrogen atoms, 0.5 to 1.2 weight percent silicon-bonded hydroxyl groups, and less than 5 percent silicon-bonded alkoxy groups where the alkoxy group is methoxy or ethoxy.

45. (New) A composition according to Claim 28 wherein (b) comprises 60 to 90 mole percent of  $\text{RSiO}_{3/2}$  units, less than 5 mole percent of  $\text{SiO}_{4/2}$  units, 50 to 80 mole percent silicon-bonded phenyl groups, 13.7 to 20 mole percent silicon-bonded hydrogen atoms, 0.5 to 1.2 weight percent silicon-bonded hydroxyl groups, and less than 5 percent silicon-bonded alkoxy groups where the alkoxy group is methoxy or ethoxy.

46. (New) A composition according to Claim 37 wherein (b) comprises 60 to 90 mole percent of  $\text{RSiO}_{3/2}$  units, less than 5 mole percent of  $\text{SiO}_{4/2}$  units, 50 to 80 mole percent silicon-bonded phenyl groups, 13.7 to 20 mole percent silicon-bonded hydrogen atoms, 0.5 to 1.2 weight percent silicon-bonded hydroxyl groups, and less than 5 percent silicon-bonded alkoxy groups where the alkoxy group is methoxy or ethoxy.